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Part Number: [0739425200](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73942](#)
Application Backplane
Comments Solder Tail
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.118 In
PC Tail Length (mm) 3.00 mm
PCB Retention None
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C

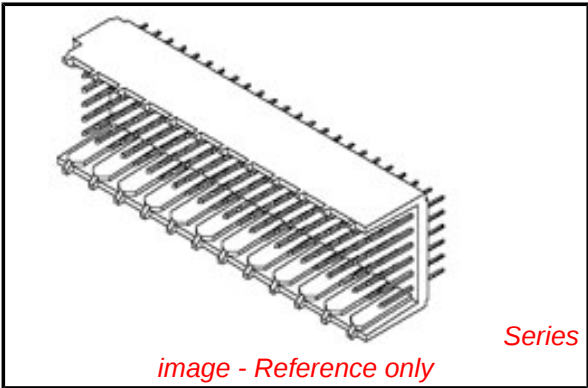


image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73942Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

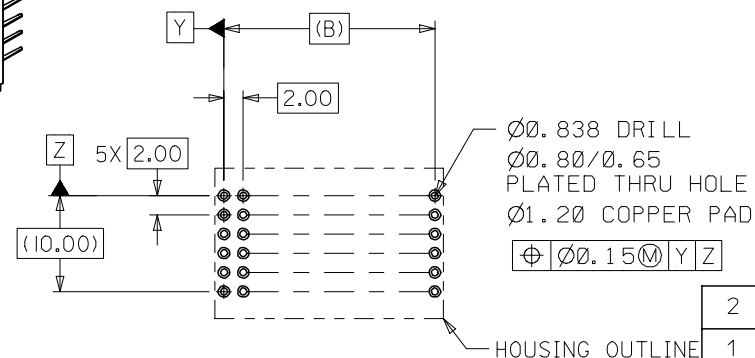
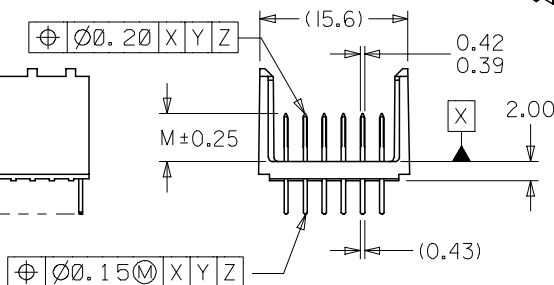
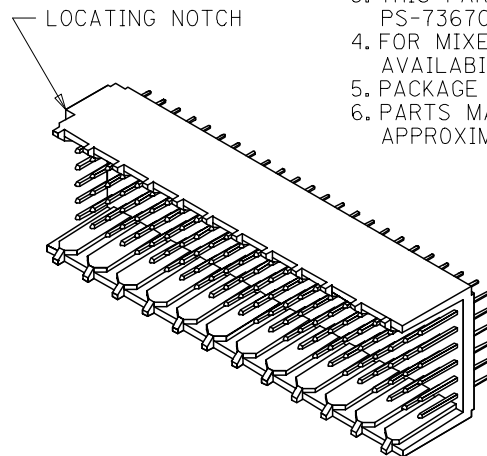
Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED,
UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA;
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION
PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR
AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE,
APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

	2	A
E	1	G
	SHT	REV

- SEE NOTE 6

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRAWN BY: IBARRA 2007/03/13 CHK'D BY: BARKER 2007/03/21 APPR: MILLER 2007/03/22	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY JB INGHAM	DATE 1998/01/13	TITLE SALES ASSY HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION			
			4 PLACES	± ---	± ---	CHECKED BY SREED	DATE 1998/01/13				
			3 PLACES	± ---	± ---	APPROVED BY CB IXLER	DATE 1998/01/13				
			2 PLACES	± 0.05	± ---	MOLEX MOLEX INCORPORATED		MOLEX INCORPORATED			
			1 PLACE	± 0.10	± ---						
			ANGULAR ±1/2°		MATERIAL NO.	DOCUMENT NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-73942-001		1 OF 2					
SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

MATERIAL NUMBER ASSIGNMENT

73942-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	23.84	22.00	2.0
1	144	47.84	46.00	2.0
2	72	23.84	22.00	2.5
3	144	47.84	46.00	2.5
4	72	23.84	22.00	3.0
5	144	47.84	46.00	3.0
6	72	23.84	22.00	3.5
7	144	47.84	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC No. U81577 DRWN:JBINGHAM 98/0203 CHK: SREED 98/0203 APPR:CBIXLER 98/0203 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE --:--	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
					DRAWN BY & DATE JBINGHAM 98/01/13			TITLE: SALES ASSY, HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION		REVISE ON CAD ONLY	
			4 PLACES ±0. ±.		CHECKED BY & DATE SREED 98/01/13			MOLEX INCORPORATED			
			3 PLACES ±0. ±.		APPROVED BY & DATE CBIXLER 98/01/13						
			2 PLACES ±0.N/A ±.		CAD FILENAME S73942X2.DGN			MATERIAL NO. SEE CHART		DRAWING NO. SD-73942-001	
1 PLACE ±0.N±A ±.		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR: ± °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B			